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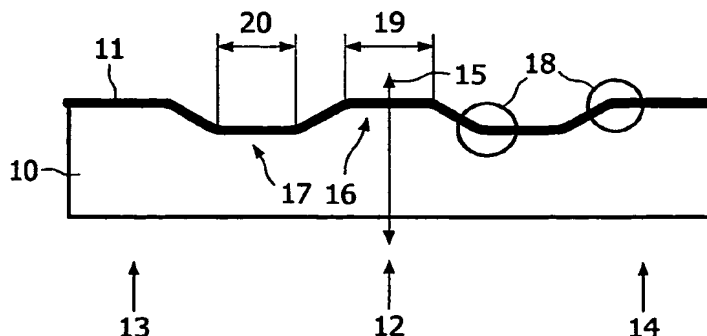
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(57) Abstract: A device such as a flexible  
AMLCD is described comprising first (10)  
and second layers (11), wherein the first layer  
is a flexible substrate and the second layer is  
a brittle ITO conduction line applied to the  
substrate. The ITO layer has a corrugated  
structure and is in contact with the substrate  
along a substantial portion of the length of the  
ITO layer so as to prevent fracture of the ITO  
layer when the flexible substrate is deformed.  
The ITO layer may be divided into portions  
(16, 17), the length of the portions being  
selected to prevent fracture when the flexible  
substrate is deformed to a predetermined  
radius of curvature.



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